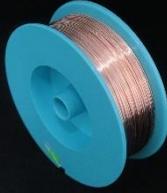
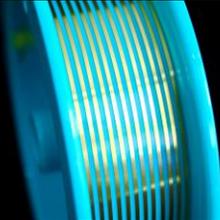
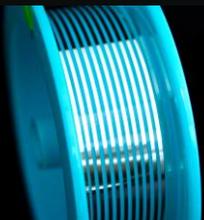


TANAKA's Bonding Wire

List of types

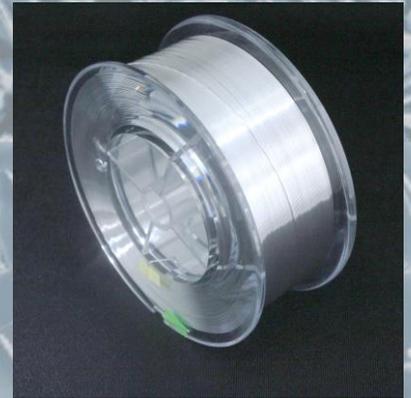
		Material			
		Gold	Silver	Copper	Aluminum
Type	Fine Wire				
	Coated Fine Wire				
	Thick Wire				
	Ribbon				



Aluminum Bonding Wire / TANW

Characteristics

- Excellent corrosion resistance.
- Excellent bondability.
- Wire diameter : $\Phi 100 - 500\mu\text{m}$
- Length : Max 800m ($\Phi 300\mu\text{m}$ / No.88K)

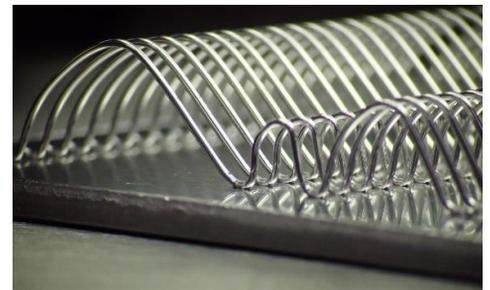


($\Phi 300\mu\text{m}$ / No.88K)

Cross Section after PCT test

Time (hrs)	20	100	1000
TANW			
Pure Al			

Looping image

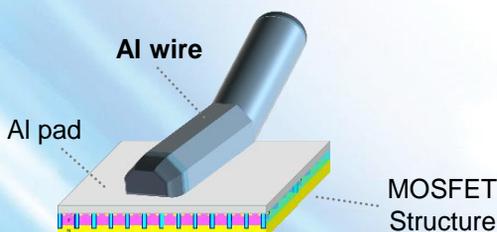


$\Phi 300\mu\text{m}$

Wire Dia. : $300\mu\text{m}$ PCT : at 121°C , 100% RH, 2atm

Applications

For Power Devices (MOSFET, IGBT)



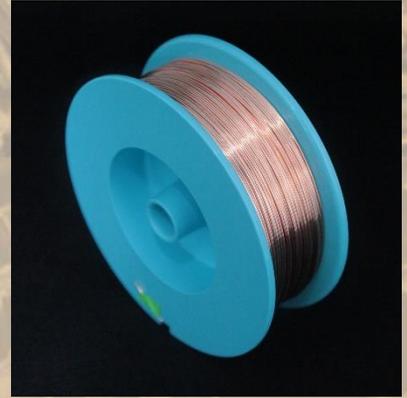
For Cell Connection



Copper Bonding Wire / CP-1

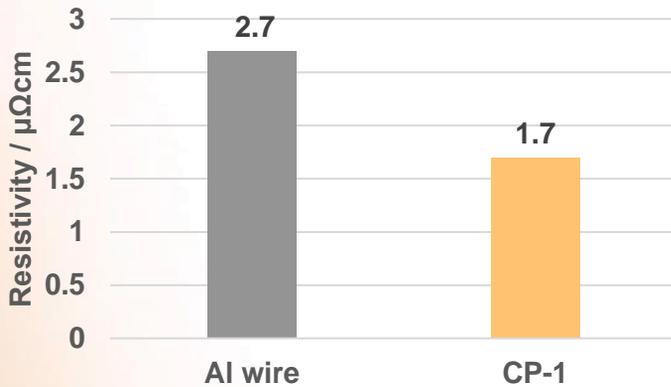
Characteristics

- Excellent electrical conductivity.
- High fusing current.
- Wire diameter : $\Phi 100 - 500\mu\text{m}$



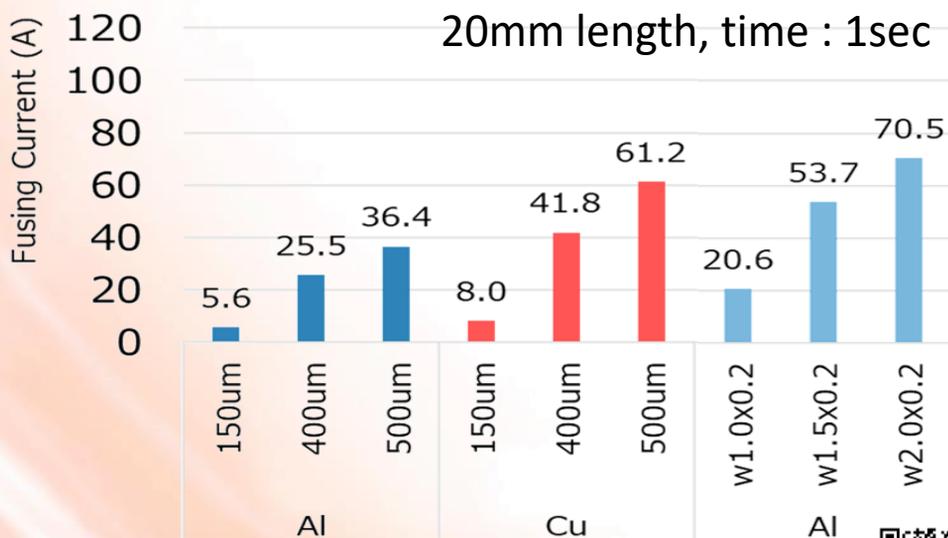
($\Phi 300\mu\text{m}$ / No.88)

Resistivity



Looping image

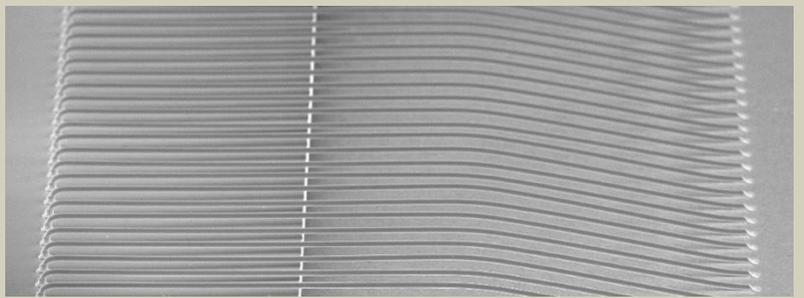
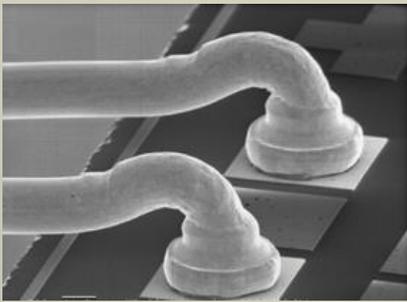
Fusing current



Gold Bonding Wire

Characteristics

- Excellent bonding reliability
- Excellent bondability
- Wire diameter : $\Phi 15 - 80\mu\text{m}$



Palladium Coated Copper Wire

Characteristics

- Low cost (90% less than Gold Wire)
- Good bonding reliability
- Wire diameter : $\Phi 15 - 80\mu\text{m}$

